APPLICA	BLE STAN	DARD									
	OPERATING TEMPERATURE RANGE		−35°C TO + 85°C(I	NOTE1)	STORAGE TEMPERAT	URE RANG	E	-10°C TO + 60°C		(NOTE3)	
RATING	OPERATING HUMIDITY RANGE		20 % TO 80 %(NO	TE2)		IIDITY RANGE 40 % TO 70 %		40 % TO 70 %	(NOTE3)		
	VOLTAGE		AC/DC 100V		APPLICABL CONNECTO			DF50A-*S-			
	CURRENT		AWG 28 : 1.0 AWG 30 : 0.9		APPLICAB CONTACT			DF50-2830SCFA			
	1				TIONS	<u> </u>					
TI	EM		TEST METHOD			R	EQL	JIREMENTS	QT	АТ	
CONSTR	RUCTION										
GENERAL EXAMINATION VISUALL		Y AND BY MEASURING INSTRUMENT.		ACCC	ACCORDING TO DRAWING.			X	X		
MARKING CONFIR		CONFIRM	MED VISUALLY.			1			Х	X	
	IC CHARA										
			,			30m $Ω$ MAX.				_	
INSULATION RESISTANC		100V DC.			500MΩ	500MΩ MIN.				-	
VOLTAGE P	ROOF	300V AC FOR 1 min.			NO FL	NO FLASHOVER OR BREAKDOWN.				_	
MECHAN	NICAL CHA	RACT	ERISTICS		I				_	<u> </u>	
		30TIMES	S INSERTIONS AND EXTRACTIONS.			 CONTACT RESISTANCE: 50mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			X	_	
0.75		0.75 mm	QUENCY 10 TO 55 Hz, SINGLE AMPLITUDE mm, AT 10 CYCLE FOR EACH, FOR 3 ECTIONS.			1 NO ELECTRICAL DISCONTINUITY OF 1µs. 2 NO DAMAGE, CRACK OR LOOSENESS OF PARTS. X				_	
1		1	DURATION OF PULSE 11 ms MES FOR 3 DIRECTIONS.								
ENVIRO	NMENTAL	CHAR	ACTERISTICS						_		
DAMP HEAT	-	EXPOSE	D AT 40 ± 2 °C, 90 TO 95 9	%, 96 h.	① CC	ONTACT R	ESIS	STANCE: 50mΩ MAX.			
(STEADY STATE)						 INSULATION RESISTANCE: 100MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			X	_	
RAPID CHANGE OF TEMPERATURE		TIME UNDER 5	DER 5 CYCLES. E TRANSFERRING TIME OF THE TANK			 CONTACT RESISTANCE: 50mΩ MAX. INSULATION RESISTANCE: 500MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			X	_	
COUN	T DI	ESCRIPTI	ON OF REVISIONS	С	DESIGNED	GNED CHECKED		С	ATE		
						1					
				APPROVED		KI. AKIYAMA	10.	07. 06			
					CHECKED (OM. MIYAMOTO	10. 07. 05			
						DESIGNED		TT. OHSAKO		10. 07. 05	
					DRAWN		TT. OHSAKO 1		07. 05		
Note QT:Qualification Test AT:Assuran			surance Test X:Applicable Te	Test X:Applicable Test DF				ELC4-332937-00			
			CATION SHEET	F	PART NO.	DF50A-*P-1V(DF50A-*P-1V(51)		
		HIROSE ELECTRIC CO., LTD.			ODE NO.	CL665-		Δ	1/2		

FORM HD0011-2-1

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE,	SOLDER SHALL COVER A MINIMUM OF	.,	
	245°C FOR INSERTION DURATION, 5 sec.	95 % OF THE SURFACE BEING IMMERSED.	X	-
RESISTANCE TO	1) REFLOW SOLDERING	NO DEFORMATION OF CASE OF		
SOLDERING HEAT	≪REFLOW AREA≫	EXCESSIVE LOOSENESS OF THE	X	-
	MAX250°C WITHIN 10 sec	TERMINALS.		
	MIN 220°C WITHIN 60 sec			
	《PREHEATING AREA》			
	150~180°C 90~120s			
	2) MANUAL SOLDERING SOLDERING IPON TEMPERRATURE 350±10°C			
	SOLDERING TIME 3~4s.			
	NO STRENGTH ON CONTACT.			
1			<u> </u>	L

REMARKS

NOTE 1: INCLUDING THE TEMPERATURE RISE BY CURRENT.

NOTE 2: NON-CONDENSING

NOTE 3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD.

AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION

Unless otherwise specifid , refer to JIS C 5402.

Note QT:Qu	ualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.		ELC4-332937-00		
HRS	SPECIFICATION SHEET	PART NO.	DF50A-*P-1V(51)			
	HIROSE ELECTRIC CO., LTD.	CODE NO		CL665-	A	2/2